Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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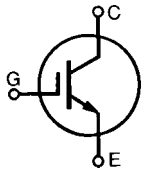
IXYS

HiPerFAST™ IGBT

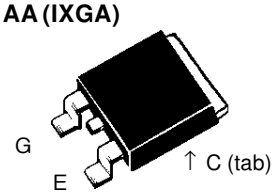
IXGA 12N60C
IXGP 12N60C

V_{CES} = 600 V
I_{C25} = 24 A
$V_{CE(sat)}$ = 2.7 V
$t_{fi(typ)}$ = 55 ns

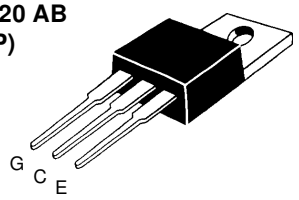


Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C; R_{GE} = 1 MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C	24	A
I_{C90}	T_C = 90°C	12	A
I_{CM}	T_C = 25°C, 1 ms	48	A
SSOA	V_{GE} = 15 V, T_{VJ} = 125°C, R_G = 33 Ω	I_{CM} = 24	A
(RBSOA)	Clamped inductive load, L = 300 µH	@ 0.8 V_{CES}	
P_C	T_C = 25°C	100	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
M_d	Mounting torque with screw M3	0.45/4	Nm/lb.in.
	Mounting torque with screw M3.5	0.55/5	Nm/lb.in.
Weight		4	g
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C

TO-263 AA (IXGA)



TO-220 AB (IXGP)



G = Gate C = Collector
E = Emitter TAB = Collector

Symbol (T_J = 25°C, unless otherwise specified)	Test Conditions		Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250 µA, V_{GE} = 0 V		600			V
$V_{GE(th)}$	I_C = 250 µA, V_{GE} = V_{GE}		2.5		5.0	V
I_{CES}	V_{CE} = 0.8, V_{CES}	T_J = 25°C			200	µA
	V_{GE} = 0 V	T_J = 125°C			1	mA
I_{GES}	V_{CE} = 0 V, V_{GE} = ±20 V				±100	nA
$V_{CE(sat)}$	I_C = I_{CE90}, V_{GE} = 15			2.1	2.7	V

Features

- Very high freqency IGBT
- New generation HDMOS™ process
- International standard package JEDEC TO-220AB and TO-263AA
- High peak current handling capability

Applications

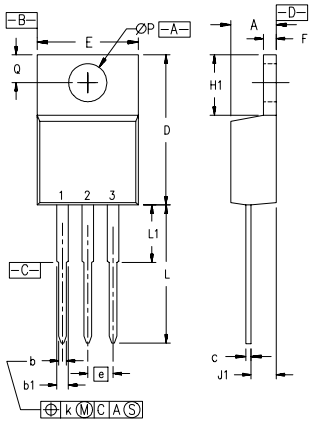
- PFC circuits
- AC motor speed control
- DC servo & robot drives
- Switch-mode and resonant-mode power supplies
- High power audio amplifiers

Advantages

- Fast switching speed
- High power density

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	$I_C = I_{C90}$; V_{CE} = 10 V, Pulse test, t ≤ 300 µs, duty cycle ≤ 2 %	7	11		S
C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz		860		pF
C_{oes}			64		pF
C_{res}			15		pF
Q_g	$I_C = I_{C90}$, V_{GE} = 15 V, V_{CE} = 0.5 V_{CES}		32		nC
Q_{ge}			10		nC
Q_{gc}			10		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		20		ns
t_{ri}	$I_C = I_{C90}$, V_{GE} = 15 V, L = 300 µH		20		ns
$t_{d(off)}$	V_{CE} = 0.8 V_{CES}, $R_G = R_{off}$ = 18 Ω		60		ns
t_{fi}	Remarks: Switching times may increase for V_{CE} (Clamp) > 0.8 V_{CES}, higher T_J or increased R_G		55		ns
E_{off}			0.09		mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		20		ns
t_{ri}	$I_C = I_{C90}$, V_{GE} = 15 V, L = 300 µH		20		ns
E_{on}	V_{CE} = 0.8 V_{CES}, $R_G = R_{off}$ = 18 Ω		0.15		mJ
$t_{d(off)}$	Remarks: Switching times may increase for V_{CE} (Clamp) > 0.8 V_{CES}, higher T_J or increased R_G		85	180	ns
t_{fi}			85	180	ns
E_{off}			0.27	0.60	mJ
R_{thJC}				1.25	K/W
R_{thCK}			0.25		K/W

TO-220 AB Dimensions

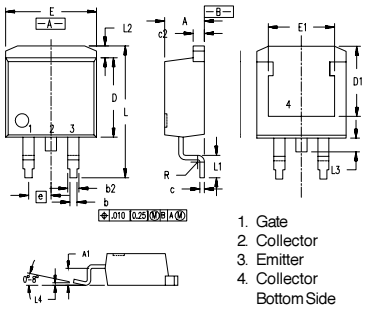


Pins: 1 - Gate 2 - Collector
3 - Emitter 4 - Collector
Bottom Side

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-220 AB.

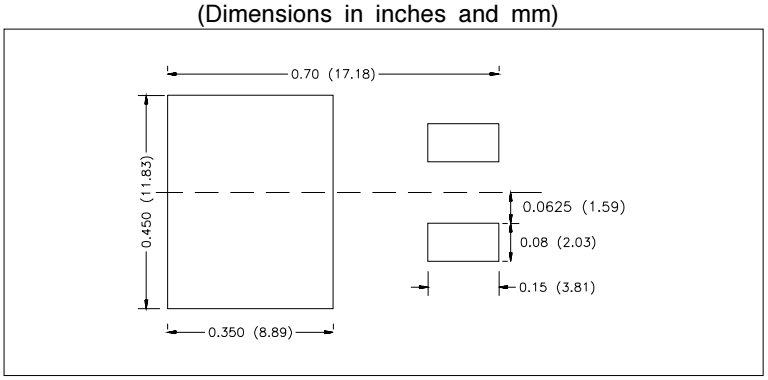
TO-263 AA Outline



1. Gate
2. Collector
3. Emitter
4. Collector
Bottom Side

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.06	4.83	.160	.190
A1	2.03	2.79	.080	.110
b	0.51	0.99	.020	.039
b2	1.14	1.40	.045	.055
c	0.46	0.74	.018	.029
c2	1.14	1.40	.045	.055
D	8.64	9.65	.340	.380
D1	7.11	8.13	.280	.320
E	9.65	10.29	.380	.405
E1	6.86	8.13	.270	.320
e	2.54	BSC	.100	BSC
L	14.61	15.88	.575	.625
L1	2.29	2.79	.090	.110
L2	1.02	1.40	.040	.055
L3	1.27	1.78	.050	.070
L4	0	0.38	0	.015
R	0.46	0.74	.018	.029

Min. Recommended Footprint
(Dimensions in inches and mm)



IXYS reserves the right to change limits, test conditions, and dimensions.

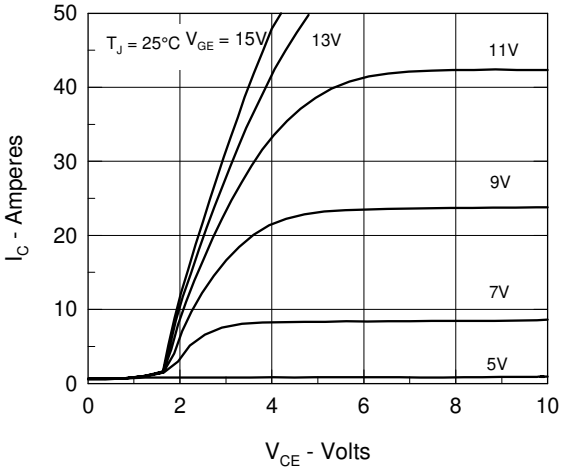


Fig. 1. Saturation Voltage Characteristics

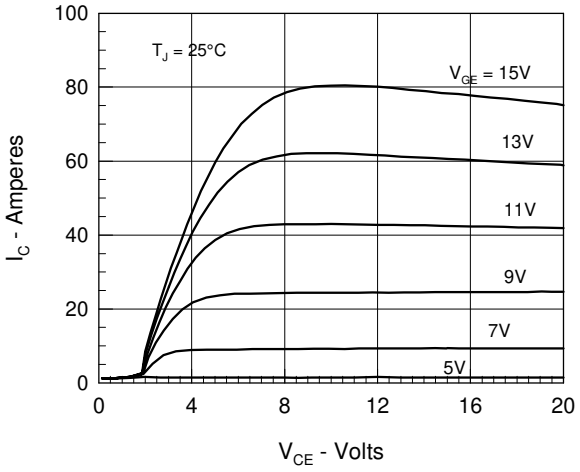


Fig. 2. Extended Output Characteristics

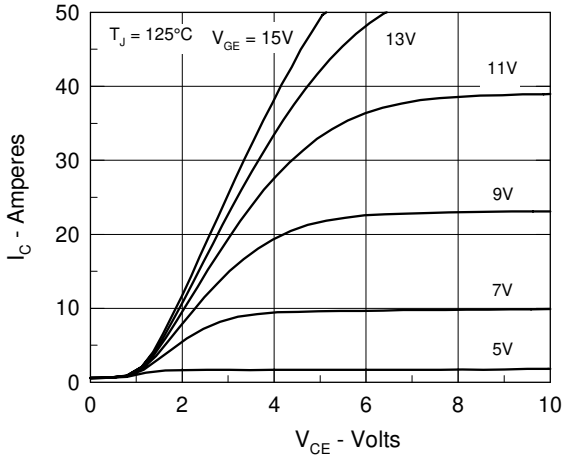


Fig. 3. Saturation Voltage Characteristics

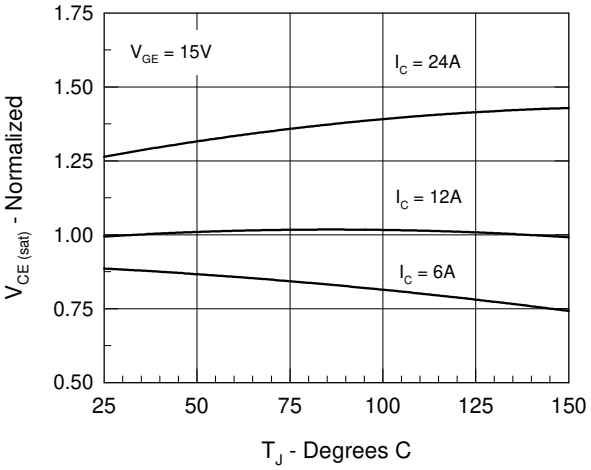


Fig. 4. Temperature Dependence of $V_{CE(sat)}$

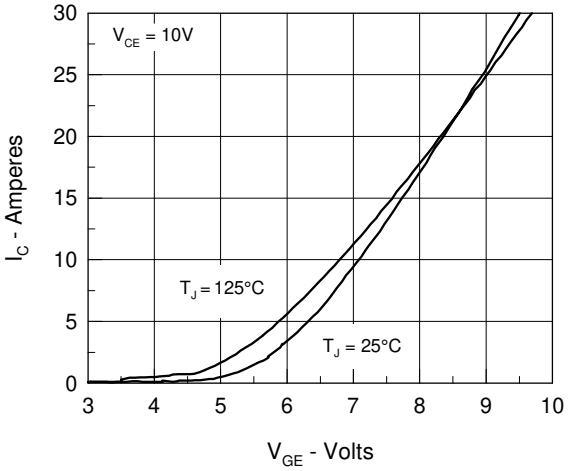


Fig. 5. Saturation Voltage Characteristics

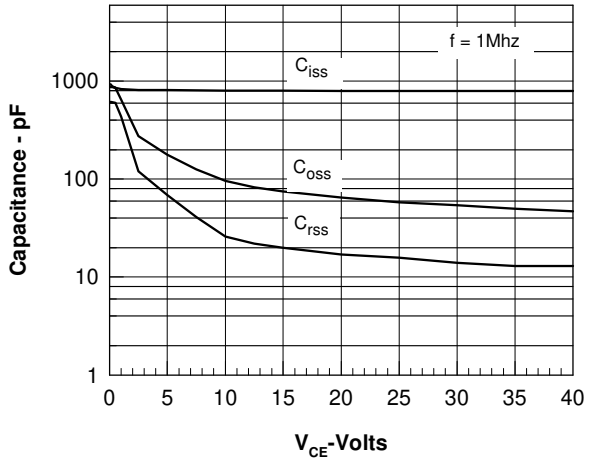


Fig. 6. Junction Capacitance Curves

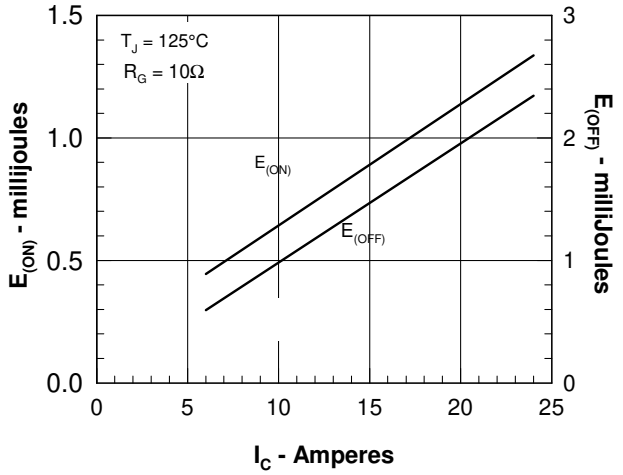


Fig. 7. Dependence of E_{ON} and E_{OFF} on I_C.

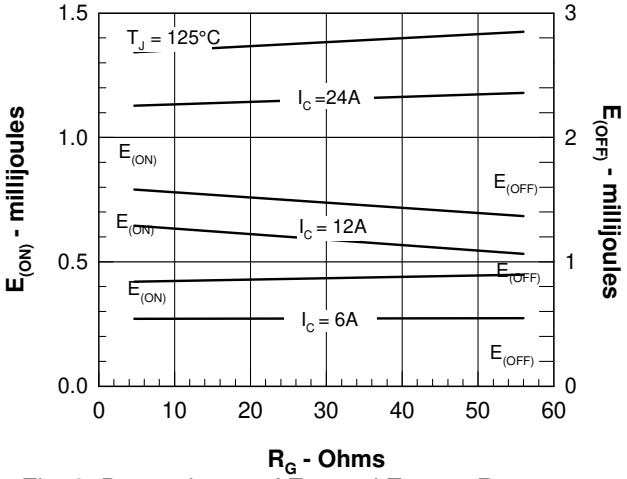


Fig. 8. Dependence of E_{ON} and E_{OFF} on R_G.

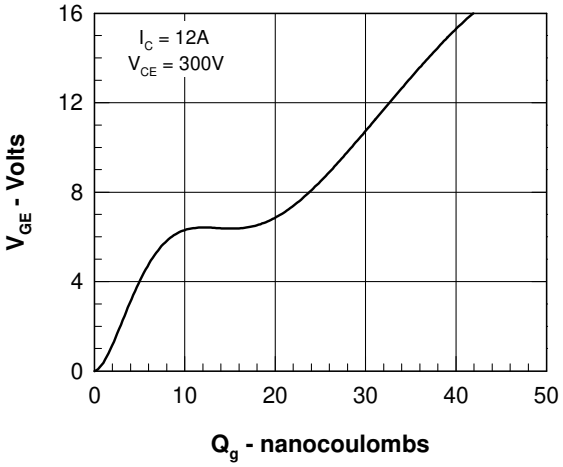


Fig. 9. Gate Charge

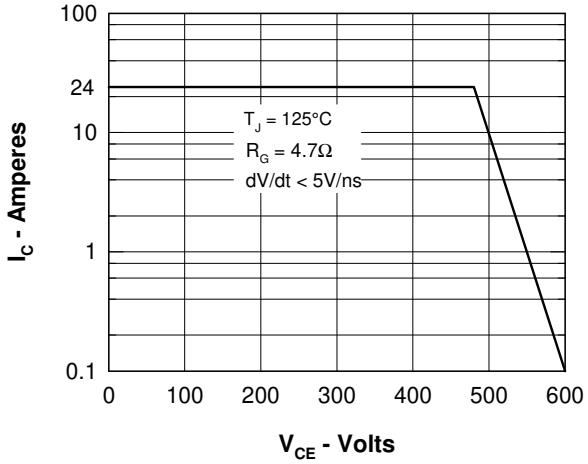


Fig. 10. Turn-off Safe Operating Area

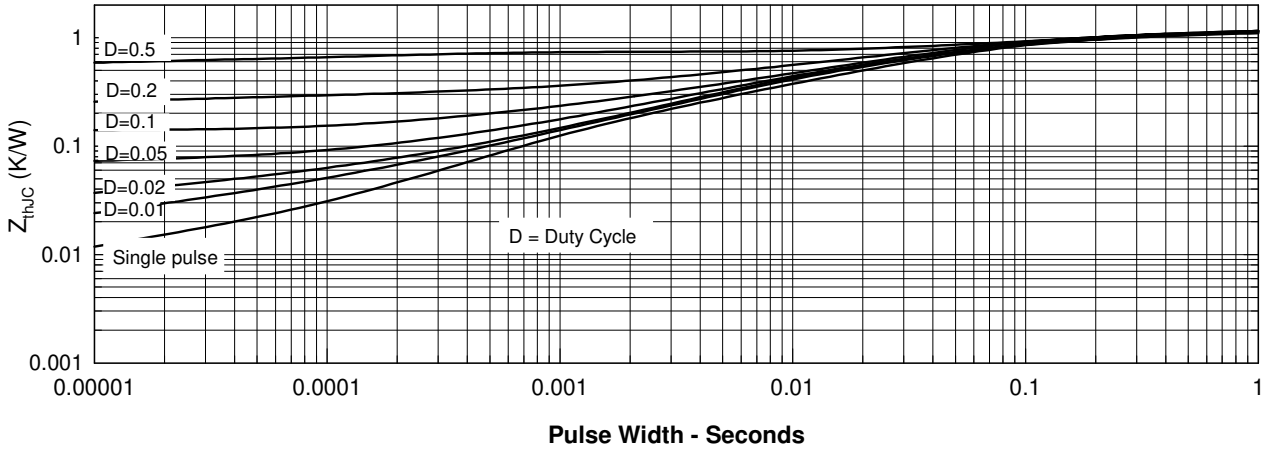


Fig. 11. Transient Thermal Resistance